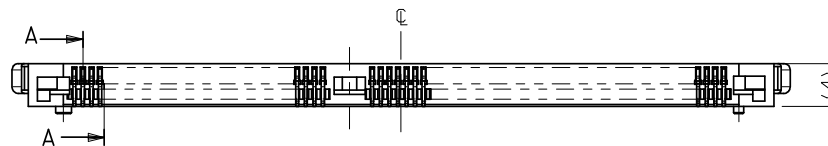
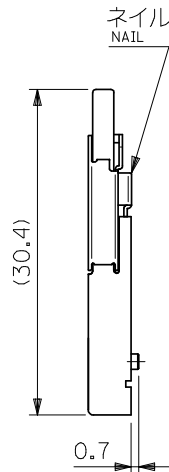
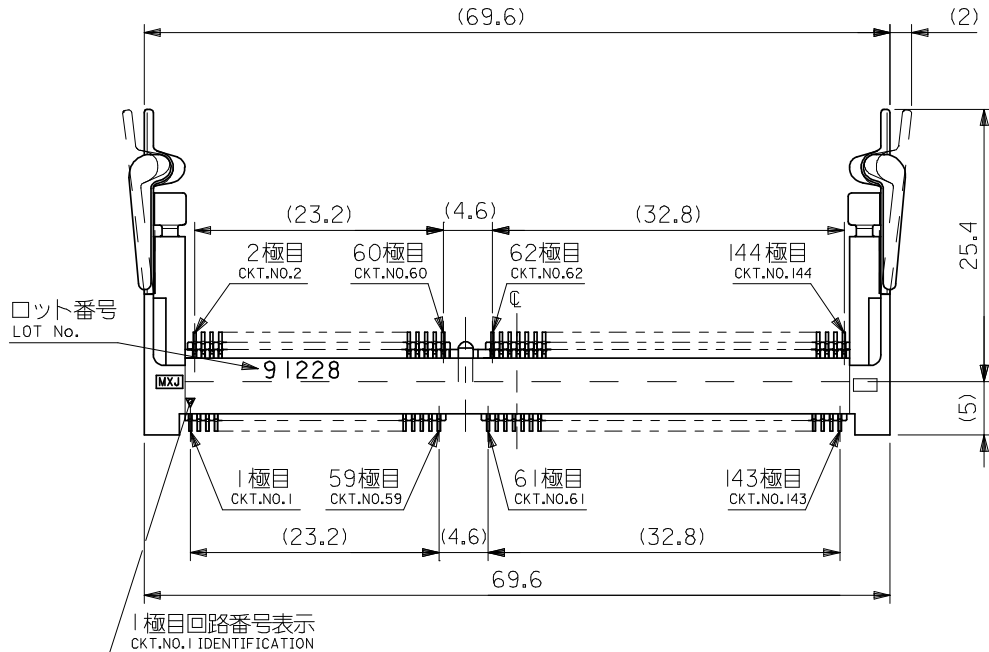


詳細 D
DETAIL D
(SCALE:5-1)

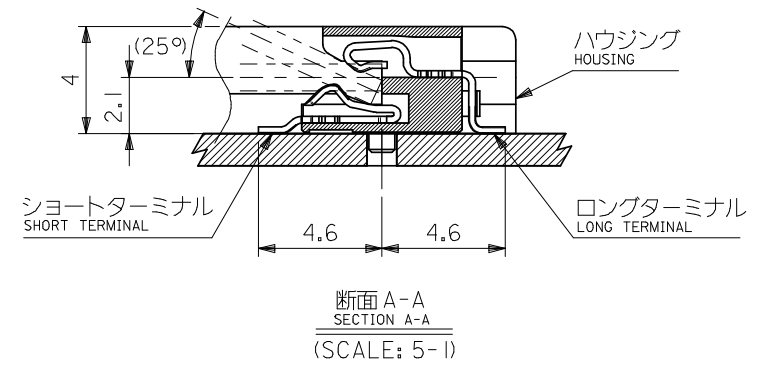
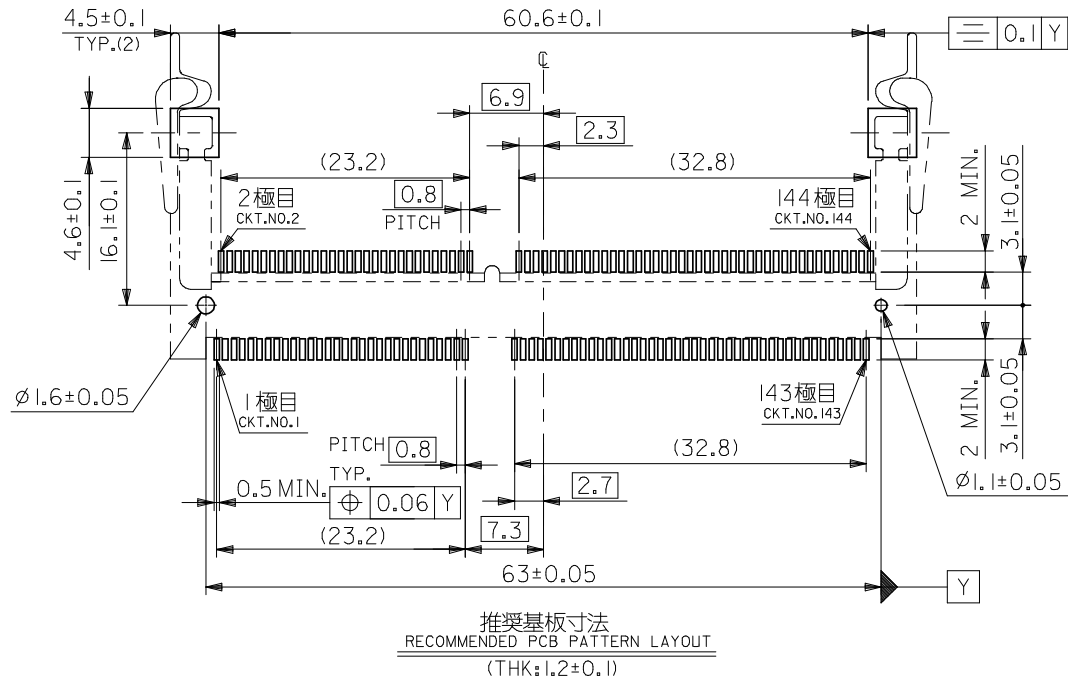
注記 1. 材料 ハウジング : ガラス入り耐熱樹脂、白色、UL94V-0
MATERIAL HOUSING : G.F.HEAT RESISTANT PLASTIC,WHITE,UL94V-0
ターミナル : 磷青銅
TERMINAL : PHOSPHOR BRONZE
ネイル : 黄銅
NAIL : BRASS

2. めっき仕様
PLATING
ロングターミナル
LONG TERMINAL
接点部 : 金めっき 0.25μmMIN.
CONTACT AREA : GOLD 0.25 μmMIN.
半田付け部 : 半田めっき 1.0μmMIN.
SOLDER TAIL AREA : TIN-LEAD 1.0μmMIN.
下地めっき : ニッケルめっき 2.0μmMIN.
UNDER-PLATING : NICKEL 2.0μmMIN.
ショートターミナル
SHORT TERMINAL
接点部 : 金めっき 0.25μmMIN.
CONTACT AREA : GOLD 0.25 μmMIN.
半田付け部 : 金めっき 0.3μmMAX.
SOLDER TAIL AREA : GOLD 0.3μmMAX.
下地めっき : ニッケルめっき 2.0μmMIN.
UNDER-PLATING : NICKEL 2.0μmMIN.
ネイル
NAIL
半田めっき : 2.0μmMIN.
TIN-LEAD : 2.0μmMIN.
3. テール平坦度は、0.1 MAX.とする。
TAIL COPLANARITY TO BE 0.1 MAX.
ネイル平坦度は、0.1 MAX.とする。
NAIL COPLANARITY TO BE 0.1 MAX.

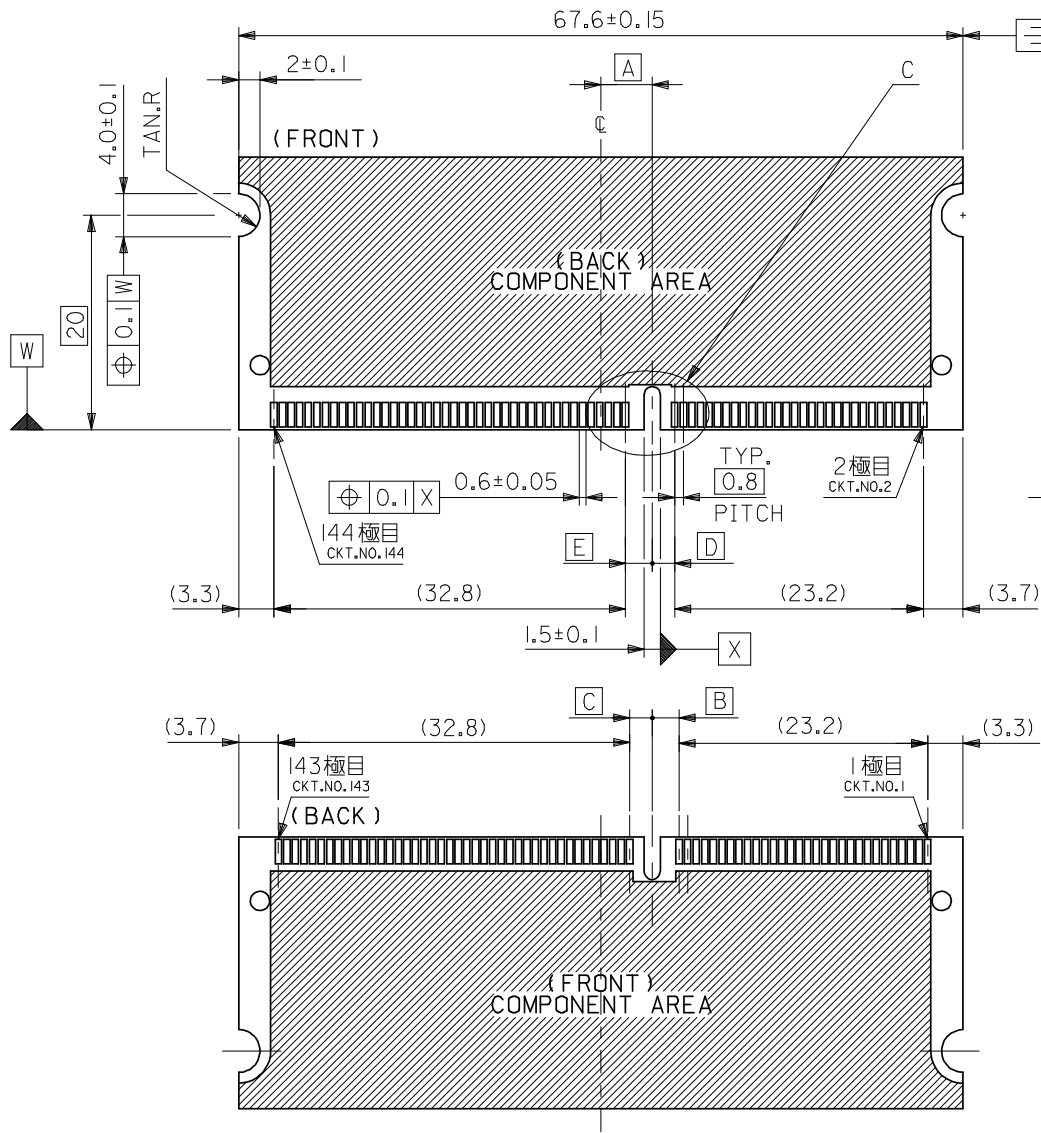


2.5	2.1	2.1	2.5	4.8	3.3V	標準トレイ NORMAL TRAY	54697-1440	54697-144*
E	D	C	B	A	POWER SUPPLY	梱包トレイ PACKAGING TRAY	MATERIAL NO.	MODEL NO.

REVISED EC NO: J2008-1539 DRW:KI INOSHITA 2008/04/09 CHK: T. HARUYAMA 2008/04/09 APPR: NUKITA 2008/06/09	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY T. KANEKO	DATE '99/9/27	TITLE 0.8MM PITCH S.O.DIMM SOCKET 144CKT. HEIGHT 4MM			
	10 OVER 30 UNDER	±0.25	CHECKED BY J. MIYAZAWA	DATE '99/9/27				
	30 OVER	±0.3	APPROVED BY H. IKESUGI	DATE '99/9/27	MOLEX INCORPORATED			
	ANGULAR	±3 °	MATERIAL NO.	DOCUMENT NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE		SD-54697-001			SHEET NO. 1 OF 3



REVISED EC NO: J2008-1539 DRW:K INOSHITA 2008/04/09 CHK:D T. HARUYAMA 2008/04/09 APPR: NUKITA 2008/06/09	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY T. KANEKO	DATE '99/9/27	TITLE 0.8MM PITCH S.O.DIMM SOCKET 144CKT. HEIGHT 4MM			
	10 OVER 30 UNDER	±0.25	CHECKED BY J. MIYAZAWA	DATE '99/9/27				
	30 OVER	±0.3	APPROVED BY H. IKESUGI	DATE '99/9/27	MOLEX INCORPORATED			
	ANGULAR	±3 °	MATERIAL NO. SEE SHEET 1					
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



推奨基板寸法
RECOMMENDED MATING BOARD CONFIGURATION
(THK:1.0±0.1)

REVISED EC NO: J2008-1539 DRAWN: K INOSHITA 2008/04/09 CHKD: T HARUYAMA 2008/04/09 APPR: NUKITA 2008/06/09	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY T. KANEKO	DATE '99/9/27	TITLE 0.8MM PITCH S.O.DIMM SOCKET 144CKT. HEIGHT 4MM	
	10 OVER 30 UNDER	±0.25	CHECKED BY J. MIYAZAWA	DATE '99/9/27	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY H. IKESUGI	DATE '99/9/27	DOCUMENT NO. SD-54697-001	SHEET NO. 3 OF 3
	ANGULAR	±3 °	MATERIAL NO. SEE SHEET 1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3			